ABSTRACT

A method and an assembly of the invention are intended for connecting two parts via a spacer made from a heat-shrinkable material shrinkable only in one direction. The spacer is sandwiched between the parts and attached to both parts with such orientation that direction of the shrinkage of the spacer coincides with the direction of movement of both parts towards each other. After the parts and the spacer are interconnected, the spacer is heated for causing said parts to move closer to each other. The space between the parts can be filled with an adhesive material so that the parts will be held together without the use of clamps or binding bands while the adhesive is cured. Another application is to attach a heatsink to an electronic device supported by a PC board. Shrinkage of the spacer under effect of heating brings the electronic device into a tight heat-transferring contact with the heatsink and maintains this contact irreversibly. Another embodiment of the invention provides a spacer made from electroconductive heat-shrinkable material and is used not only for improving a heat-transfer contact between the source of heat and the heatsink, but also for grounding the heatsink against EMI.